Silicon N-Channel Power MOS FET Module

HITACHI

Application

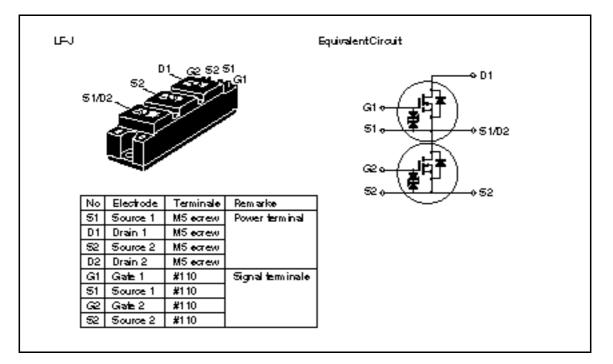
High Speed Power Switching

Features

- Equipped with Power MOS FET
- Low on-resistance
- High speed switching
- Low drive current
- Wide area of safe operation
- Inherent parallel diode between source and drain
- Isolated base from Terminal
- Suitable for motor driver, switching regulator and etc.



Outline



Absolute Maximum Ratings (Ta = 25°C) (Per FET chip)

Symbol	Rating	Unit V	
V _{(BR)DSS}	500		
V _{(BR)GSS}	±30	V	
I _D	75	А	
l _{D(peak)}	180	А	
I _{DR}	75	А	
I DR(peak)	180	А	
Pch*1	300	W	
Tch	150	°C	
Tstg	-45 to +125	°C	
Viso*2	2000	Vrms	
	V(BR)DSS V(BR)GSS ID ID(peak) IDR IDR(peak) Pch*1 Tch Tstg	V 500 V 500 ID 500 ID 75 ID 75 IDD 75 IDD 75 IDD 75 IDDR 75 IDDR 75 IDDR 75 IDDR 75 IDDR 180 Pch*1 300 Tch 150 Tstg -45 to +125	

Notes: 1. Value at Ta = 25°C

2. Base to terminals AC minute

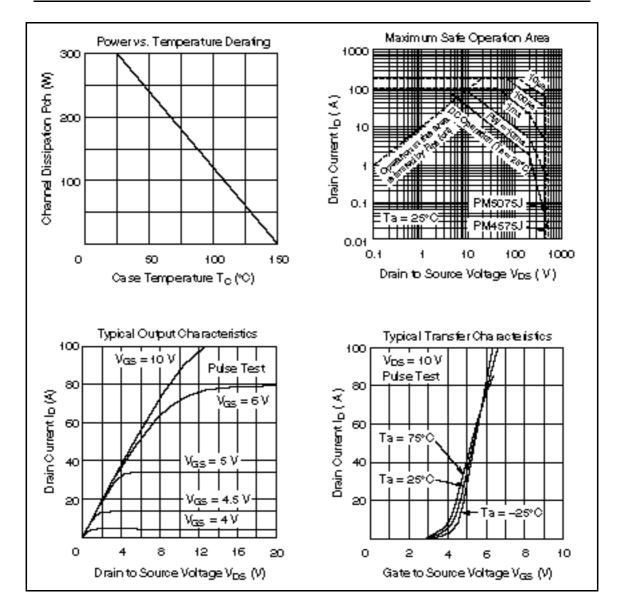
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	500	_	_	V	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate to source leak current	I _{GSS}		_	±10	μA	$V_{\text{GS}} = \pm 25 \text{ V}, V_{\text{DS}} = 0 \text{ V}$
Gate to source breakdown voltage	$V_{(\text{BR})\text{GSS}}$	±30	_	_	V	$I_{g} = \pm 100 \ \mu A, \ V_{DS} = 0 \ V$
Drain leak current	I _{DSS}		_	500	μA	$V_{\rm DS} = 400 \ V, \ V_{\rm GS} = 0 \ V$
Gate to source threshold voltage	$V_{\text{GS(th)}}$	2.0	_	3.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Drain to source saturation voltage	$V_{\text{DS(on)}}$		3.7	4.44	V	$I_{\rm D} = 37$ A, $V_{\rm GS} = 10$ V* ¹
Static drain-source on state resistance	$R_{\text{DS(on)}}$		0.10	0.12		$I_{\rm D} = 37$ A, $V_{\rm GS} = 10$ V*1
Forward transfer admittance	y _{fs}	_	45	_	S	$I_{\rm D} = 37$ A, $V_{\rm DS} = 10$ V ^{*1}
Input capacitance	Ciss		9600		pF	$V_{\rm DS} = 10 \ V, \ V_{\rm GS} = 0 \ V$
Output capacitance	Coss		2300			f = 1 MHz
Reverse transfer capacitance	Crss		330		_	
Turn-on delay time	t _{d(on)}		100		ns	$I_{\rm D} = 37$ A, $V_{\rm GS} = 10$ V
Rise time	t _r		310	_	_	Rg = 50
Turn-off delay time	t _{d(off)}	_	550	_	-	R _L = 1
Fall time	t _f	_	135	_	_	
Body to drain diode forward voltage	V_{DF}		1.8	—	V	$I_F = 75 \text{ A}, V_{GS} = 0 \text{ V}$
Body to drain diode reverse recovery time	t _{rr}	_	130	_	ns	$I_F = 75 \text{ A}, V_{GS} = 0 \text{ V}$ di/dt = 100 A/ μ s

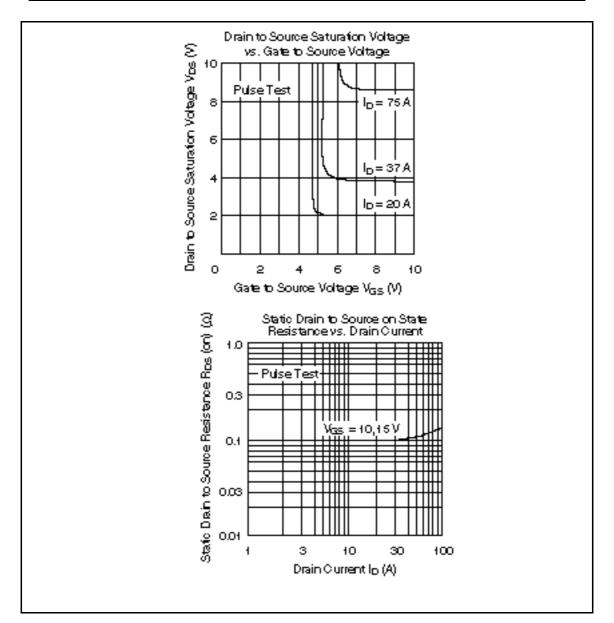
Electrical Characteristics (Ta = 25°C) (Per FET chip)

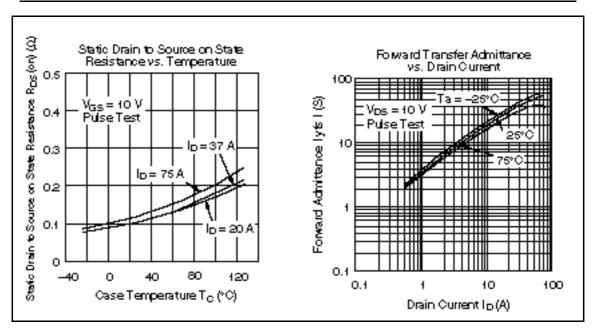
Note: 1. Pulse Test

Mechanical Characteristics

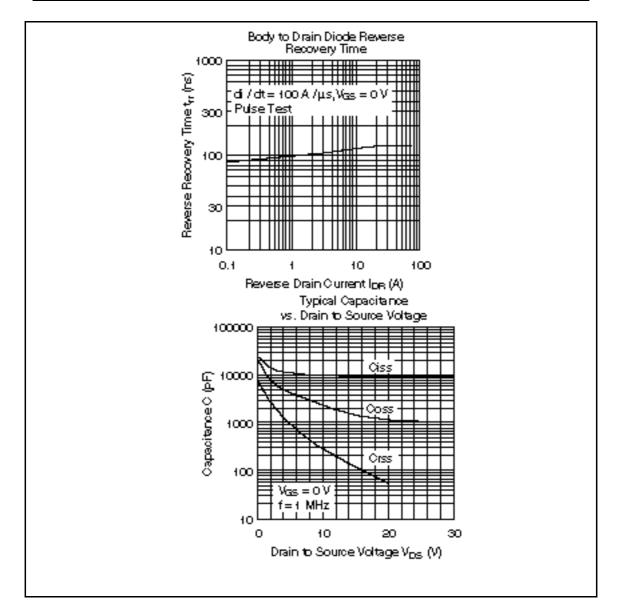
Symbol	Condition	Rating	Unit
_	Mounting into main-terminal with M4 screw	1.45 to 1.95	N-m
—	Mounting into heat sink with M5 screw	1.95 to 2.9	N-m
_	Typical value	200	g
	Symbol 	 Mounting into main-terminal with M4 screw Mounting into heat sink with M5 screw 	- Mounting into main-terminal with M4 screw 1.45 to 1.95 - Mounting into heat sink with M5 screw 1.95 to 2.9

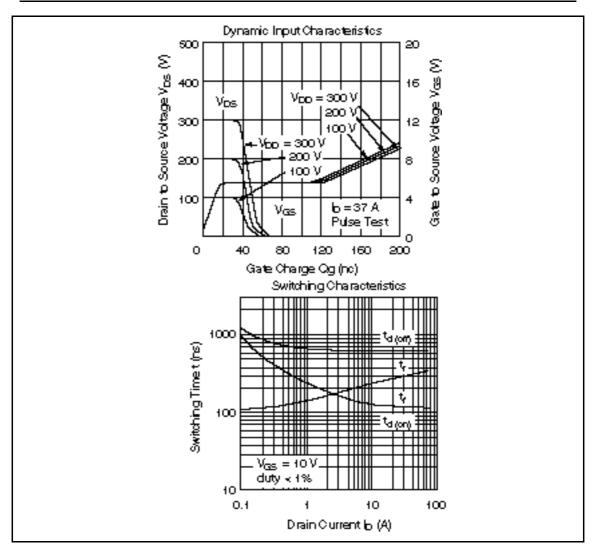


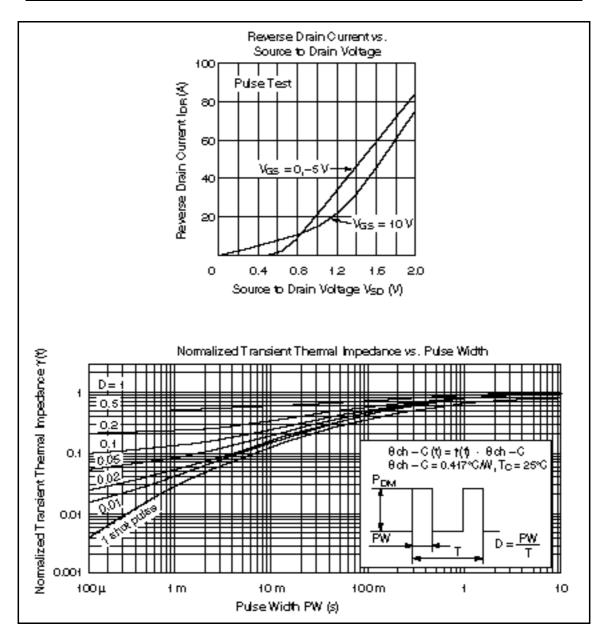


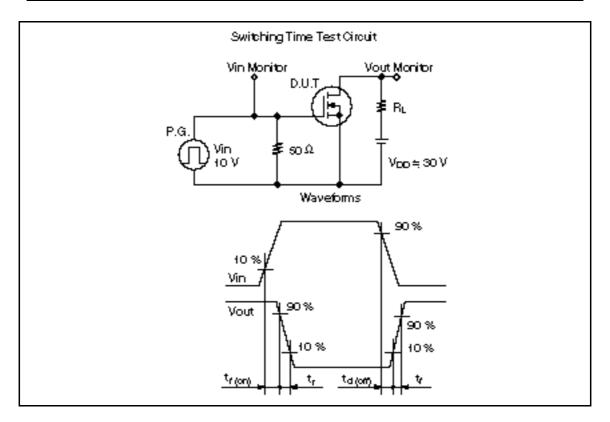


HITACHI



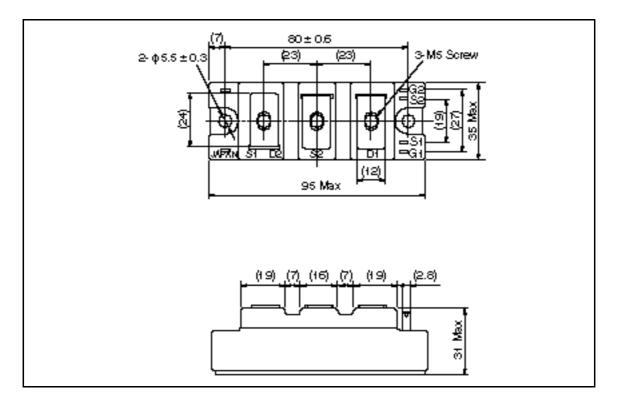






Package Dimensions

Unit: mm



When using this document, keep the following in mind:

- 1. This document may, wholly or partially, be subject to change without notice.
- 2. All rights are reserved: No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without Hitachi's permission.
- 3. Hitachi will not be held responsible for any damage to the user that may result from accidents or any other reasons during operation of the user's unit according to this document.
- 4. Circuitry and other examples described herein are meant merely to indicate the characteristics and performance of Hitachi's semiconductor products. Hitachi assumes no responsibility for any intellectual property claims or other problems that may result from applications based on the examples described herein.
- 5. No license is granted by implication or otherwise under any patents or other rights of any third party or Hitachi, Ltd.
- 6. MEDICAL APPLICATIONS: Hitachi's products are not authorized for use in MEDICAL APPLICATIONS without the written consent of the appropriate officer of Hitachi's sales company. Such use includes, but is not limited to, use in life support systems. Buyers of Hitachi's products are requested to notify the relevant Hitachi sales offices when planning to use the products in MEDICAL APPLICATIONS.

HITACHI

Hitachi, Ltd. Semiconductor 4. IC DV. Nepon Bidg, 2-5-2, Ohte-mach, Chiyoda-ku, Tokyo 100, Japan Tet Tokyo (03, 3270-2111 Fax (03, 3270-5109

For Author in forms Ion write to : Hischi America, Ud Semiconductor & IC DV. 2000 Sierre Point Pertwey Briebene, CA. 94005-4835 U S.Å Tet 415-583-8300 Fax: 415-583-4207

Hitschi Burope GmbH Bedronic Components Group Cartisnertsi Burope Danscher Straße 3 D-85522 Fieldkirchen Mänchen Tet 083-9 94 80-0 Fex 083-9 29 30 00 Hitschi Europe Ltd. Bectronic Components Div. Northern Burge Hesdguerters Whitsbrock Ferk Lower Cook hem Roed Neidenhesd Berkshire SL6SYA United Kingdom Tet 0628-355000 Fex 0628-778222 Hitschi Asia Pte. Ltd 45 Collyer Quey \$20-00 Hitschi Tower Singspore 0404 Tet 535-2400 Fex: 535-4533

Hitschi Asia (Hong Kong) Ltd. Unit 705, North Towar, World Finance Cantre, Herbour City, Carton Road Taim Sha Tau, Kowloon Hong Kong Tet 27350218 Fax: 27306074

HITACHI